

Electronic Patent Application Fee Transmittal

| Application Number: | 10723474 | | | |
|--|--|-----------------|---------------|-----------------------------|
| Filing Date: | 26-Nov-2003 | | | |
| Title of Invention: | Electronic apparatus having an adhesive layer from wafer level packaging | | | |
| First Named Inventor/Applicant Name: | Suan Jeung Boon | | | |
| Filer: | Suneel Arora/Amy Moriarty | | | |
| Attorney Docket Number: | 303.601US2 | | | |
| Filed as Large Entity | | | | |
| Utility Filing Fees | | | | |
| Description | Fee Code | Quantity | Amount | Sub-Total in USD(\$) |
| Basic Filing: | | | | |
| Pages: | | | | |
| Claims: | | | | |
| Miscellaneous-Filing: | | | | |
| Petition: | | | | |
| Patent-Appeals-and-Interference: | | | | |
| Post-Allowance-and-Post-Issuance: | | | | |
| Extension-of-Time: | | | | |
| Extension - 1 month with \$0 paid | 1251 | 1 | 120 | 120 |

| Description | Fee Code | Quantity | Amount | Sub-Total in USD(\$) |
|--------------------------|----------|----------|--------|----------------------|
| Miscellaneous: | | | | |
| Total in USD (\$) | | | | 120 |